Switch-mode Power Rectifier

DPAK Surface Mount Package

This switch-mode power rectifier which uses the Schottky Barrier principle with a proprietary barrier metal, is designed for use as output rectifiers, free wheeling, protection and steering diodes in switching power supplies, inverters and other inductive switching circuits.

Features

- Low Forward Voltage
- 150°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Compact Size
- Lead Formed for Surface Mount
- SBRD8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 75 Units Per Plastic Tube
- ESD Rating:
 - Machine Model = C (> 400 V)
 - Human Body Model = 3B (> 8000 V)



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SCHOTTKY BARRIER RECTIFIER 8.0 AMPERES, 35 VOLTS



CASE 369C



MARKING DIAGRAM



B835LG = Specific Device Number

= Assembly Location*

= Year

A Y

G

WW

- = Work Week
- = Pb-Free Device

* The Assembly Location Code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

ORDERING INFORMATION				
Device	Package	Shipping [†]		
MBRD835LG	DPAK (Pb-Free)	75 Units / Rail		
SBRD8835LG	DPAK (Pb-Free)	75 Units / Rail		
SBRD8835LG-VF01	DPAK (Pb-Free)	75 Units / Rail		
MBRD835LT4G	DPAK (Pb-Free)	2,500 / Tape & Reel		
SBRD835LT4G-VF01	DPAK (Pb-Free)	2,500 / Tape & Reel		
SBRD8835LT4G	DPAK (Pb-Free)	2,500 / Tape & Reel		
SBRD8835LT4G-VF01	DPAK (Pb-Free)	2,500 / Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure BRD8011/D

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	35	V
Average Rectified Forward Current (At Rated V_R , $T_C = 88^{\circ}C$)	I _{F(AV)}	8.0	A
Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, T _C = 80°C)	I _{FRM}	16	А
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz)	I _{FSM}	75	A
Repetitive Avalanche Current (Current Decaying Linearly to Zero in 1 μ s, Frequency Limited by T _{Jmax})	I _{AR}	2.0	A
Storage / Operating Case Temperature	T _{stg}	-65 to +150	°C
Operating Junction Temperature (Note 1)	TJ	-65 to +150	°C
Voltage Rate of Change (Rated V _R)	dv/dt	10,000	V/μs

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS

Symbol	Value	Unit
$R_{\theta JC}$	2.8	°C/W
R _{0JA}	80	°C/W
	R _{θJC}	$R_{\theta JC}$ 2.8

2. Rating applies when surface mounted on the minimum pad size recommended.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) ($i_F = 8 \text{ Amps}, T_C = +25^{\circ}\text{C}$) ($i_F = 8 \text{ Amps}, T_C = +125^{\circ}\text{C}$)	V _F	0.51 0.41	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_C = +25$ °C) (Rated dc Voltage, $T_C = +100$ °C)	I _R	1.4 35	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2%.

TYPICAL CHARACTERISTICS

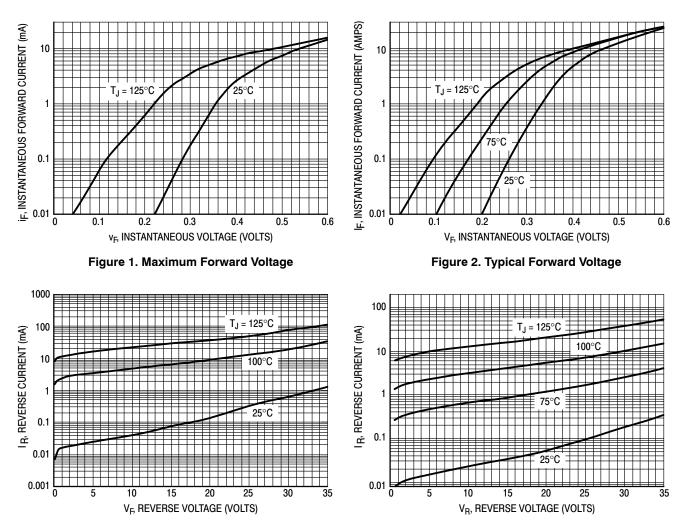
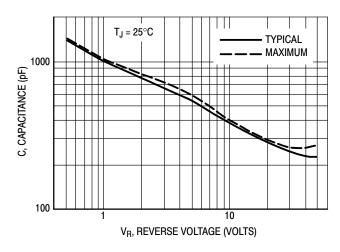
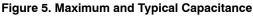


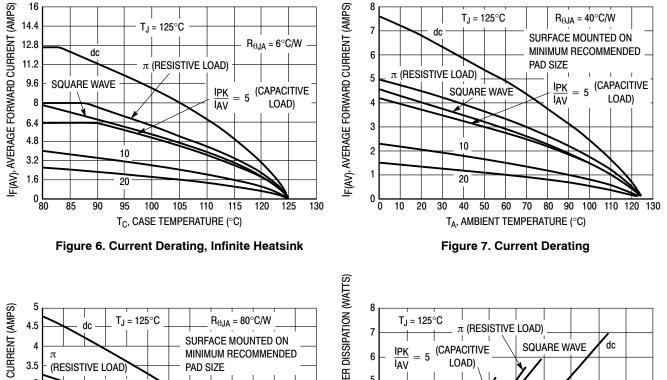
Figure 3. Maximum Reverse Current

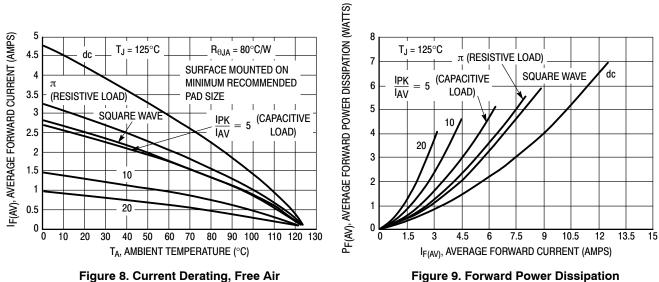


TYPICAL CHARACTERISTICS

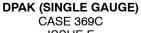




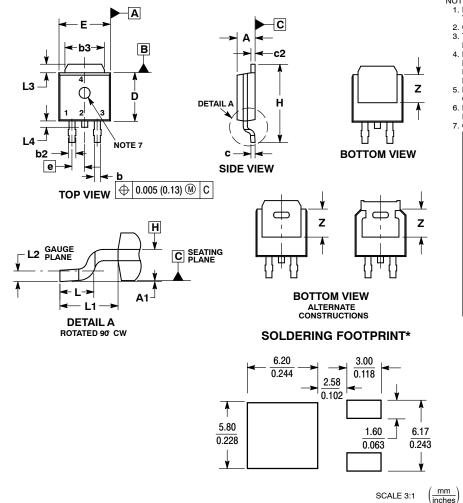




PACKAGE DIMENSIONS



ISSUE F



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NOTES:

- DILES.
 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: INCHES.
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- MENSIONS b3, L3 and Z. 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL
- NOT EXCEED 0.006 INCHES PER SIDE. 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 6. DATUMS A AND B ARE DETERMINED AT DATUM

	PLANE H.	
7		MOLD FEATURE

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
Е	0.250	0.265	6.35	6.73
е	0.090 BSC		2.29 BSC	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90	REF
L2	0.020 BSC		0.51	BSC
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Ζ	0.155		3.93	

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